

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.146447**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004926	1000000	33636.8359375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.058949	975000	402528.96875		
		Iron (Fe)	7439-89-6	0.001451	24000	9908.04882812		
		Phosphorus (P)	7723-14-0	0.000018	300	122.911705017		
		Zinc (Zn)	7440-66-6	0.000042	700	286.793945312		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.060460</b>	<b>1000000</b>	<b>412846.75</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.003400	1000000	23213.921875		
		<b>External Plating Total:</b>				<b>0.003400</b>	<b>1000000</b>	<b>23213.921875</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000484	1000000	3304.95874023		
<b>Internal Plating Total:</b>				<b>0.000484</b>	<b>1000000</b>	<b>3304.95874023</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001290	750000	8808.671875		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000430	250000	2936.22363281		
<b>Die Attach Total:</b>				<b>0.001720</b>	<b>1000000</b>	<b>11744.8945312</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb Free	Resin (EP)		0.007726	103000	52756.4335938		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.067134	895000	458419.65625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000150	2000	1024.26416016		
		<b>Encapsulation Total:</b>				<b>0.075010</b>	<b>1000000</b>	<b>512200.34375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000447	1000000	3052.30712891		
					<b>TOTAL MASS (g) :</b>	<b>0.146447</b>		